



**DEFENSE LOGISTICS AGENCY**  
 LAND AND MARITIME  
 POST OFFICE BOX 3990  
 COLUMBUS, OH 43218-3990

December 5, 2011

Mr. John DeBrita  
 DDI Global Corp - Anaheim  
 1220 N. Simon Circle  
 Anaheim, CA 92806

Dear Mr. DeBrita:

RE: Notification of Qualification, MIL-PRF-31032, CAGE: 0BSG1, VQ(VQE-12-023613),  
 CN#035026 (adjustment/new format of VQ(VQE-09-018147))

Qualification of your products is granted under the current issue of the specification as a result of successful qualification testing to Department of Defense Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specification MIL-PRF-31032 /1 & /2. The material and classification indicated below shall be listed on Qualified Manufacturers List QML-31032.

<b>MANUFACTURER INFORMATION</b>  <b>DDI Global Corp. - Anaheim</b> 1220 N. Simon Circle, Anaheim, CA, 92806 US	<b>PLANT LOCATION</b>  Same Address as Manufacturer	<b>CAGE Code: 0BSG1</b>  Mr. John DeBrita <b>Phone:</b> 714 688-7296 <b>Email:</b> jdebrita@ddiglobal.com
<b>CAPABILITIES BY TECHNOLOGY / ASSOCIATED SPECIFICATION</b>		
Specification: MIL-PRF-31032/1, MIL-PRF 31032/2		<b>QUALIFICATION LETTERS:</b>
<b>Rigid Base Material:</b> GI: Glass Base, Woven, Polyimide Resin, Heat Resistant <b>Max. Panel Size:</b> 18" x 24" <b>Max. Number of Layers:</b> 10 <b>Max. Board Thickness:</b> .1" <b>Min. Hole Size:</b> .32" Drilled Plated-Through Hole Before Plating <b>Aspect Ratio:</b> 3:1 Through-Hole <b>Min. Conductor Width/Space:</b> .01"/.01" <b>Hole Preparation:</b> Plasma Desmear, Plasma Etchback <b>Hole Wall Conductive Coating:</b> Electroless Copper <b>Copper Plating:</b> Direct Current Plate <b>Solder Resist:</b> Liquid Photoimageable <b>Finish System:</b> ENIG, HASL <b>Additional Fab Capabilities:</b> Foil Lamination <b>Controlled Impedance:</b> Differential, Single-Ended		VQ-09-018147 (initial)

<b>MANUFACTURER INFORMATION</b>  <b>DDI Global Corp. - Anaheim</b> 1220 N. Simon Circle, Anaheim, CA, 92806 US	<b>PLANT LOCATION</b>  Same Address as Manufacturer	<b>CAGE Code:</b> 0BSG1  Mr. John DeBrita <b>Phone:</b> 714 688-7296 <b>Email:</b> jdebrita@ddiglobal.com
CAPABILITIES BY TECHNOLOGY / ASSOCIATED SPECIFICATION		
Specification: MIL-PRF-31032/1, MIL-PRF 31032/2		<b>QUALIFICATION LETTERS:</b>
<b>Rigid Base Material:</b> GF: Woven E-Glass, Epoxy Resin, Flame Resistant <b>Max. Panel Size:</b> 18" x 24" <b>Max. Number of Layers:</b> 22 <b>Max. Board Thickness:</b> .115" <b>Min. Hole Size:</b> .009" Drilled Plated-Through Hole <b>Aspect Ratio:</b> 10:1 Through-Hole <b>Min. Conductor Width/Space:</b> .004"/.006" <b>Hole Preparation:</b> Plasma Desmear, Plasma Etchback <b>Hole Wall Conductive Coating:</b> Electroless Copper <b>Copper Plating:</b> Direct Current Plate <b>Hole Fill/Via Plug:</b> Conductive, Non-Conductive <b>Solder Resist:</b> Liquid Photoimageable <b>Finish System:</b> ENIG, HASL <b>Additional Fab Capabilities:</b> Foil Lamination Blind Vias Buried Vias <b>Controlled Impedance:</b> Differential, Single-Ended		VQ-09-018147 (initial)

This qualification is based on your MIL-PRF-31032 certification and is subject to the conditions:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity

of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Manufacturers are required to inform this office immediately if a failure occurs during PCI or CVI testing, if production of this qualification is discontinued, or prior to issuance of a GIDEP Alert and/or Problem Advisory on their QML products.

Because we are held responsible for the accuracy and currency of this QML, please let us know if your company discontinues production utilizing these materials or processes. If you have any questions, please contact Mr. Jeffrey Ciesla, (614) 692-0624.

Sincerely,

/SIGNED/

JOSEPH GEMPERLINE  
Chief  
Sourcing and Qualifications Division